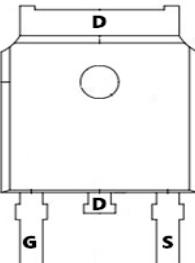
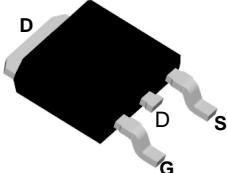
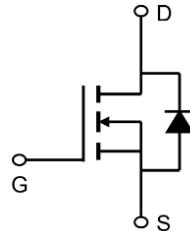


# TM80N06D

## N-Channel Enhancement Mosfet

<b>General Description</b> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <b>Applications</b> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<b>General Features</b> <p> <math>V_{DS} = 60V</math> <math>I_D = 80A</math>  <math>R_{DS(ON)} = 6.8m\Omega</math>(typ.) @ <math>V_{GS} = 10V</math>          100% UIS Tested          100% <math>R_g</math> Tested       </p> 		
 Marking 80N06	<b>D:TO-252-3L</b>  		
<b>Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)</b>			
Parameter	Symbol	Value	Unit
Drain source voltage	$V_{DS}$	60	V
Gate source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current <sup>1)</sup>	$I_D$	80	A
Pulsed drain current <sup>2)</sup>	$I_{D, \text{pulse}}$	180	A
Power dissipation <sup>3)</sup>	$P_D$	125	W
Single pulsed avalanche energy <sup>4)</sup>	$E_{AS}$	30	mJ
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	°C
Thermal resistance, junction-case	$R_{\theta JC}$	1	°C/W
Thermal resistance, junction-ambient <sup>5)</sup>	$R_{\theta JA}$	62	°C/W

**TM80N06D**
**N-Channel Enhancement Mosfet**
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-source breakdown voltage	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=250 \mu\text{A}$	60	71		V
$V_{\text{GS(th)}}$	Gate threshold voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250 \mu\text{A}$	1.0	2.0	2.5	V
$R_{\text{DS(ON)}}$	Drain-source on-state resistance	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=20 \text{ A}$		6.8	9.3	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-source on-state resistance	$V_{\text{GS}}=4.5 \text{ V}, I_{\text{D}}=10 \text{ A}$		9.2	11	$\text{m}\Omega$
$I_{\text{GSS}}$	Gate-source leakage current	$V_{\text{GS}}=20 \text{ V}$			100	nA
		$V_{\text{GS}}=-20 \text{ V}$			-100	
$I_{\text{DSS}}$	Drain-source leakage current	$V_{\text{DS}}=40 \text{ V}, V_{\text{GS}}=0 \text{ V}$			1	$\mu\text{A}$
$C_{\text{iss}}$	Input capacitance	$V_{\text{GS}}=0 \text{ V}, V_{\text{DS}}=50 \text{ V}, f=100 \text{ kHz}$		1182.1		pF
$C_{\text{oss}}$	Output capacitance			199.5		pF
$C_{\text{rss}}$	Reverse transfer capacitance			4.1		pF
$t_{\text{d(on)}}$	Turn-on delay time	$V_{\text{GS}}=10 \text{ V}, V_{\text{DS}}=50 \text{ V}, R_{\text{G}}=2 \Omega, I_{\text{D}}=10 \text{ A}$		17.9		ns
$t_r$	Rise time			4.0		ns
$t_{\text{d(off)}}$	Turn-off delay time			34.9		ns
$t_f$	Fall time			5.5		ns
$Q_g$	Total gate charge	$I_{\text{D}}=10 \text{ A}, V_{\text{DS}}=50 \text{ V}, V_{\text{GS}}=10 \text{ V}$		18.4		nC
$Q_{\text{gs}}$	Gate-source charge			3.3		nC
$Q_{\text{gd}}$	Gate-drain charge			3.1		nC
$V_{\text{plateau}}$	Gate plateau voltage			2.8		V
$I_s$	Diode forward current	$V_{\text{GS}} < V_{\text{th}}$			80	A
$I_{\text{sp}}$	Pulsed source current				180	
$V_{\text{SD}}$	Diode forward voltage	$I_s=20 \text{ A}, V_{\text{GS}}=0 \text{ V}$ $I_s=10 \text{ A}, \frac{di}{dt}=100 \text{ A}/\mu\text{s}$			1.3	V
$t_{\text{rr}}$	Reverse recovery time			41.8		ns
$Q_{\text{rr}}$	Reverse recovery charge			36.1		nC
$I_{\text{rrm}}$	Peak reverse recovery current			1.4		A

**Note**

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4)  $V_{\text{DD}}=50 \text{ V}, R_{\text{G}}=50 \Omega, L=0.3 \text{ mH}$ , starting  $T_J=25^\circ\text{C}$ .
- 5) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25^\circ\text{C}$ .

## TM80N06D

## N-Channel Enhancement Mosfet

### Electrical Characteristics Diagrams

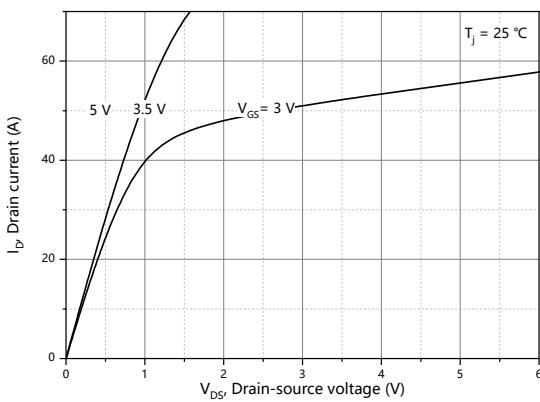


Figure 1, Typ. output characteristics

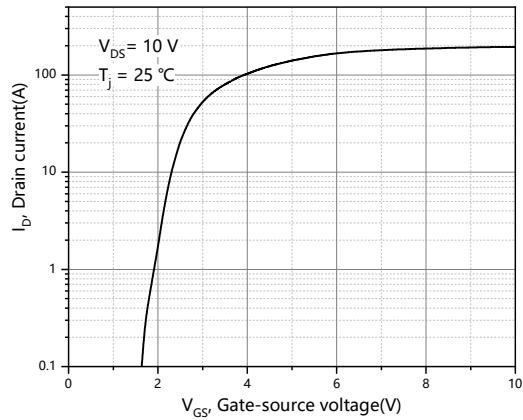


Figure 2, Typ. transfer characteristics

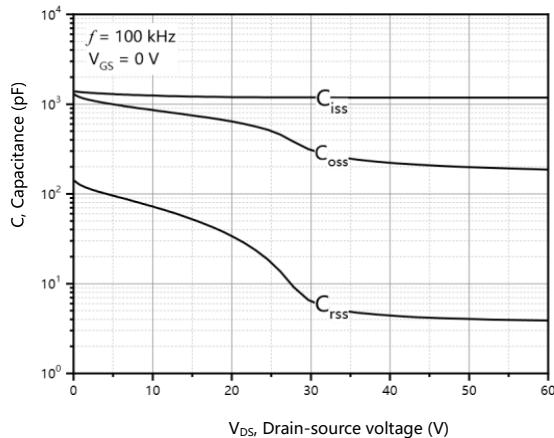


Figure 3, Typ. capacitances

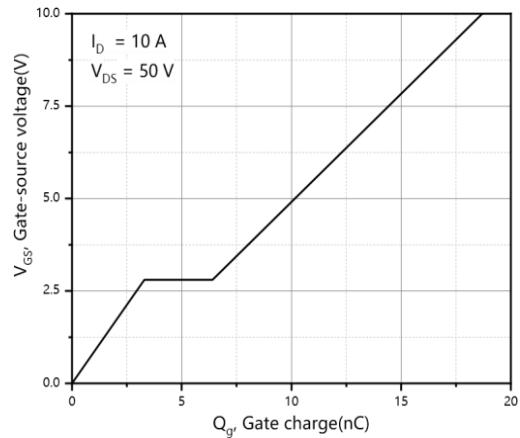


Figure 4, Typ. gate charge

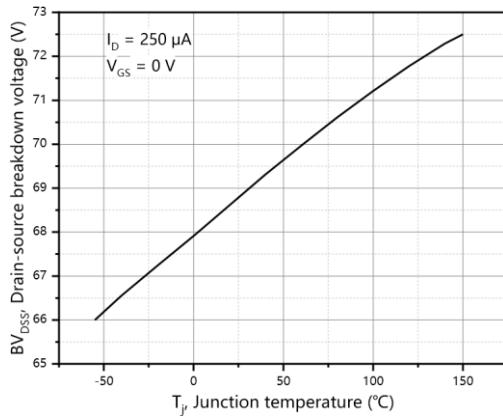


Figure 5, Drain-source breakdown voltage

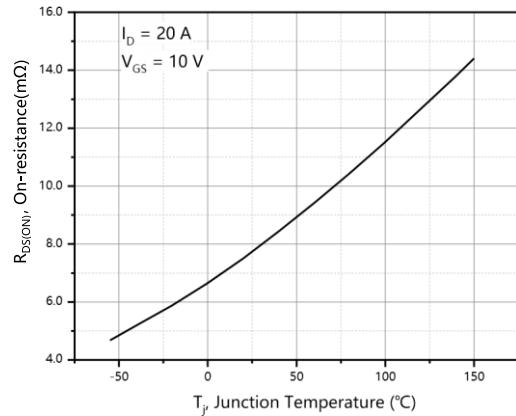


Figure 6, Drain-source on-state resistance

## TM80N06D

## N-Channel Enhancement Mosfet

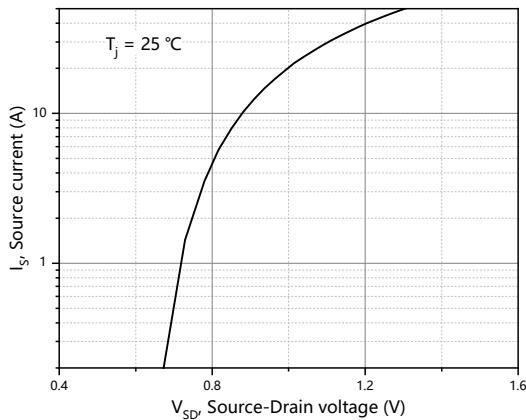


Figure 7, Forward characteristic of body diode

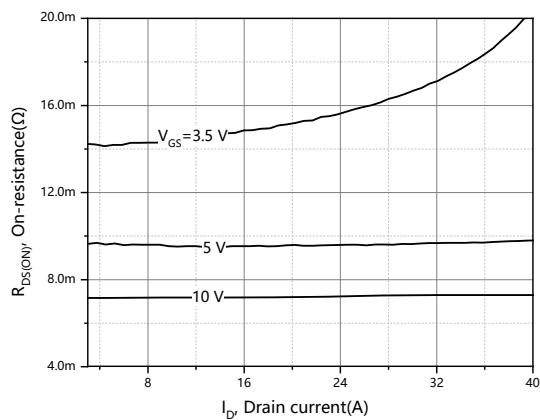


Figure 8, Drain-source on-state resistance

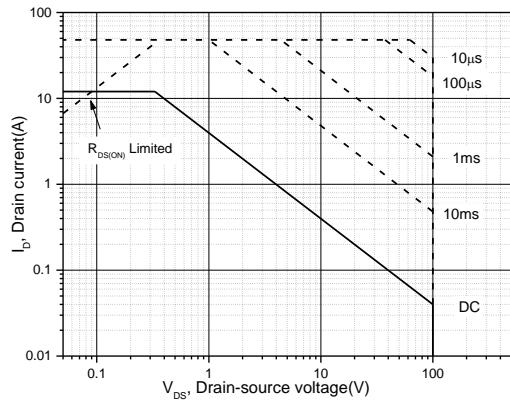


Figure 9, Safe operation area  $T_C=25\text{ }^\circ\text{C}$

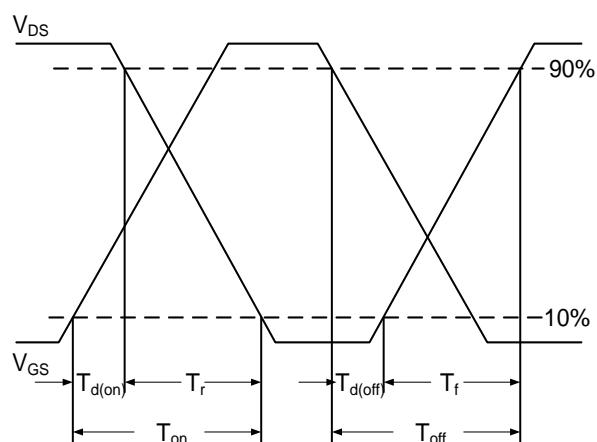


Fig.10 Switching Time Waveform

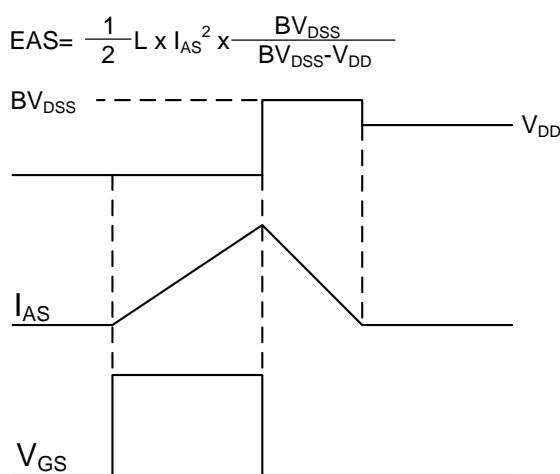
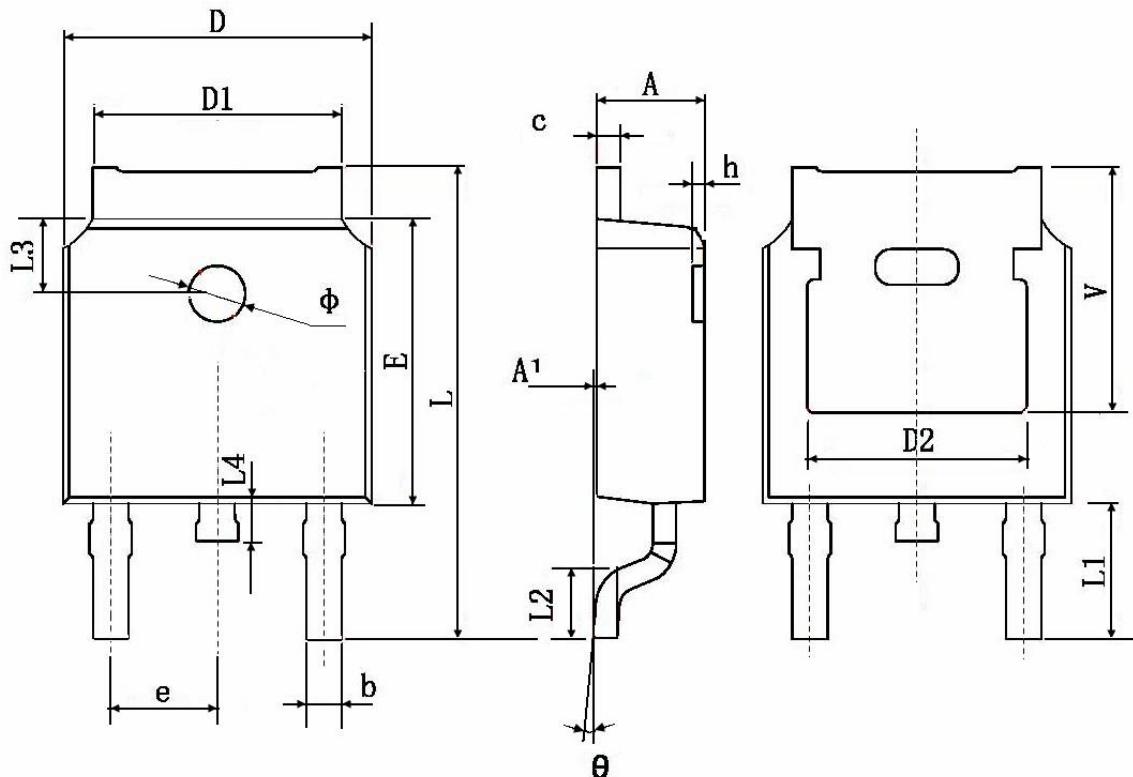


Fig.11 Unclamped Inductive Switching Waveform

## Package Information : TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
$\Phi$	1.100	1.300	0.043	0.051
$\theta$	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	